



THE EUROPEAN APPROACH FOR EXASCALE AGES

THE ROAD TOWARD SOVEREIGNTY

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Chairman of the Board

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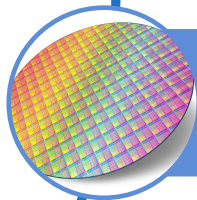
AGENDA



EPI in European HPC strategy



(post)-Exascale supercomputers specifications



(Post) Exascale processor specifications



Wrap-Up

EPI IN EUROPEAN HPC STRATEGY



CONTEXT



European Commission President Jean-Claude Juncker

Paris, 27 October 2015

« Our ambition is for Europe to become one of the top 3 world leaders in high-performance computing by 2020 »



Creation of the European processor Initiative

23 members from 10 EU countries

- General Purpose processor in 2022
- Accelerator IP

Brussels, 1 Dec 2017



Vice President Andrus Ansip

« I encourage even more EU countries to engage in this ambitious endeavour »

Digital Day Rome, 23 March 2017

Ministers from seven MS (France, Germany, Italy, Luxembourg, Netherlands, Portugal and Spain) sign a declaration to support the next generation of computing and data infrastructures



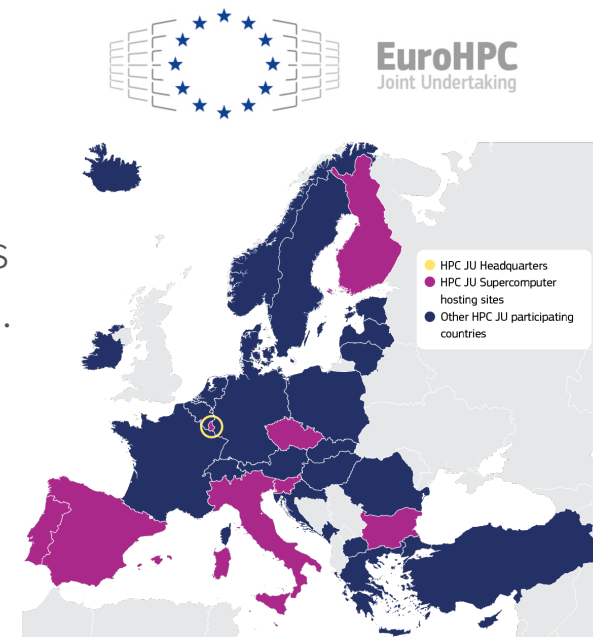
Ursula Von Der Leyen State of the Union

Brussels – September, 16th, 2020

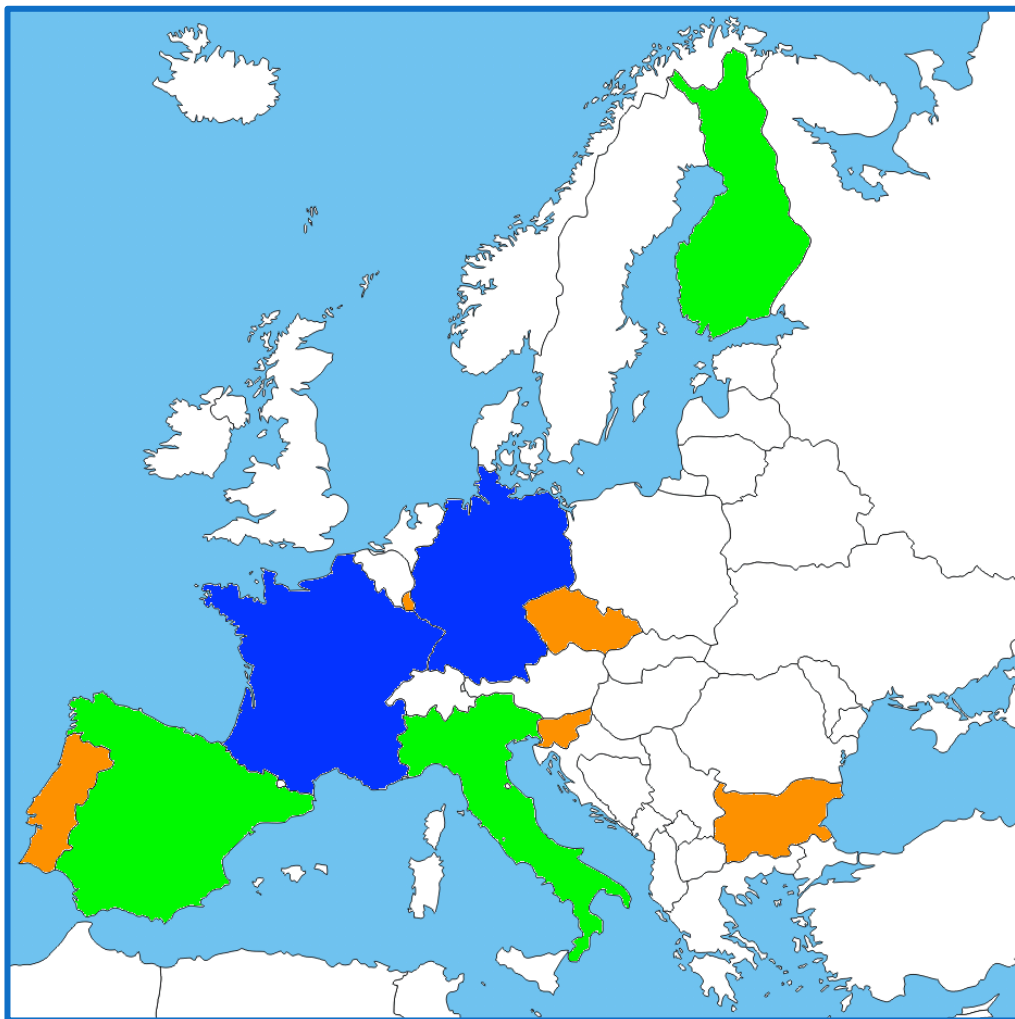
- Investment of 8 billion euros in the next generation of supercomputers - cutting-edge technology made in Europe.
- The European industry will develop our own next-generation microprocessor

EUROHPC JOINT UNDERTAKING (JU) – CONTEXT

- The European High Performance Computing Joint Undertaking (EuroHPC JU) is pooling European resources to buy and deploy top-of-the-range supercomputers and develop innovative exascale supercomputing technologies and applications.
- It aims to improve quality of life, advance science, boost industrial competitiveness, and ensure Europe's technological autonomy.
- The JU is currently supporting two main activities (2020-2021):
 - Developing a pan-European supercomputing infrastructure: 3 pre-exascale supercomputers (aim to be among the top 5 WW), and 5 petascale supercomputers. Benefit European private and public users, working in academia and industry, everywhere in Europe.
 - Supporting research and innovation activities: developing a European supercomputing ecosystem, stimulating a technology supply industry (from low-power processors to software and middleware, and their integration into supercomputing systems), and making supercomputing resources in many application areas available to a large number of public and private users, including small and medium-sized enterprises.



RECENT NEWS FROM EUROHPC



>1,000 Pflops
38 Pflops
TBD EFlops

Country	Machine	Supplier	PFLOPS	Year
Finland	LUMI	HPE	550	2021
Italy	Leonardo	ATOS	248	2021
Spain(*)	MareNostrum5	TBD	>200	2021
Luxembourg	MeluXina	ATOS	10	2021
Portugal	Deucalion	ATOS Fujitsu	10	2021
CZ Rep	IT4I (name tbd)	HPE	15,2	2021
Bulgaria	NCSA	ATOS	6	2021
Slovenia	Vega	ATOS	6,8	2021
TBD (DE?)	TBD(**)	TBD	>1,000	2023
TBD (FR?)	TBD(**)	TBD	>1,000	2024

(*) announced on Dec. 15th at the earliest

(**) with EU processor based on EPI developments)

EPI OBJECTIVES

- Overall: Develop a complete EU designed high-end microprocessor, addressing Supercomputing and edge-HPC segments. Short-term objective
 - supply the EU-designed microprocessor to empower the EU Exascale machines
 - Long-term objective
 - Europe needs a sovereign (=not at risk of limitation or embargo by non-EU countries) access to high-performance, low-power microprocessors, from IP to products
 - EPI has been set to fulfil this objective
 - EPI has to cover all Technical Readiness levels (TRL)
 - TRL 1-3 are for long-term objectives (EU IP)
- *and*
- TRL 4-9 are for short to mid-term objectives (decade) with products designed in EU



27 PARTNERS FROM 10 EU COUNTRIES

**BMW
GROUP**



Rolls-Royce
Motor Cars Limited

Atos



**Barcelona
Supercomputing
Center**
Centro Nacional de Supercomputación



KALRAY



JÜLICH
Forschungszentrum



semidynamicS
silicon design and verification services



**TÉCNICO
LISBOA**



Fraunhofer
ITWM



ALMA MATER STUDIORUM
UNIVERSITÀ DI BOLOGNA



CHALMERS



UNIVERSITÀ DI PISA



UNIVERSITY OF ZAGREB
FACULTY OF
ELECTRICAL
ENGINEERING
AND COMPUTING

E4

COMPUTER
ENGINEERING



GENCI



FORTH
INSTITUTE OF COMPUTER SCIENCE



EXTOLL
latency matters.

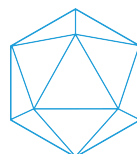


Karlsruher Institut für Technologie



PROVE & RUN

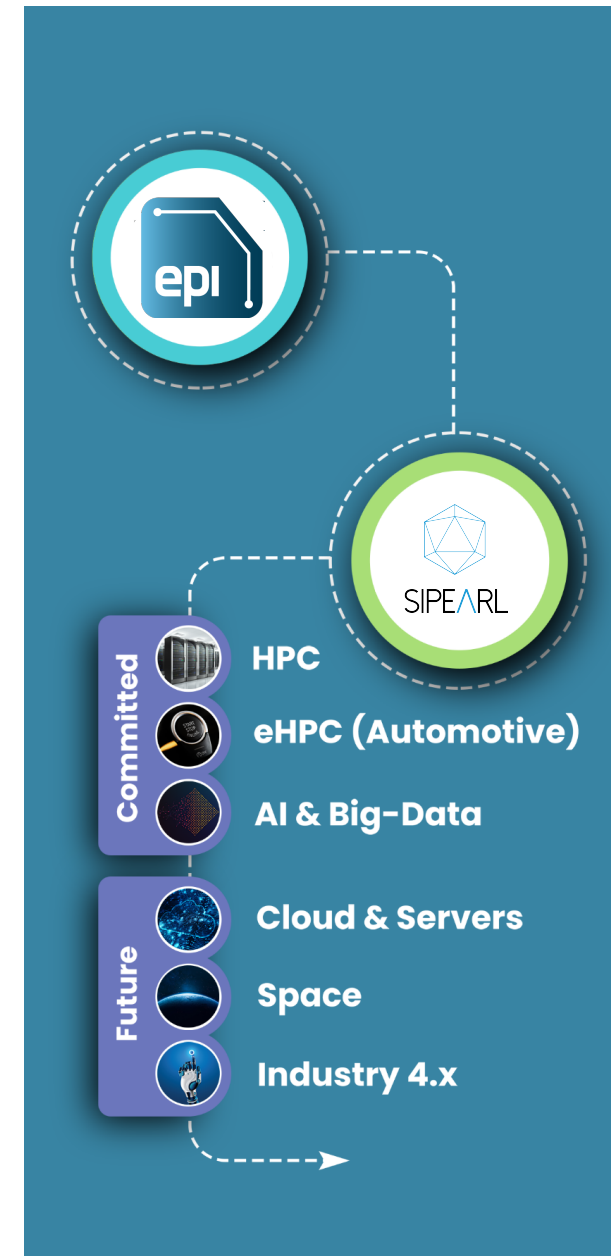
ETH zürich



SIPEARL

FROM IPR TO PRODUCTS FROM EPI TO SIPEARL

- SIPEARL is
 - Incorporated in EU (France)
 - the industrial and business 'hand' of EPI
 - the Fabless company
- licence of IPs from the partners
- develop own IPs around it
- licence the missing components from the market
- Raise in equity the missing budget (~100M€)
- generate revenue from both the HPC, IA, server and eHPC markets
- integrate, market, support & sell the chip
- work on the next generations



OVERALL ROADMAP

Dec. 2018

2019 → 2020 → 2021 →

2022

2023

>2023

Petascale
Pre-exascale

Exa

Exa

arm

Short term
objective

TRL ≥ 6

mid term
objective

RISC-V

TRL < 4

General purpose processor
(Gen1)

ARM ZEUS Core

Common Platform



EPAC IP development
& Test chip (22nm)

7nm

RHEA

GA

Gen2 development

GPP (Gen2)-
ARM > ZEUS Core

CRONOS

GA



EPAC based
Accelerator

(POST)-EXASCALE SUPERCOMPUTERS SPECIFICATIONS



HPC BEFORE ARTIFICIAL INTELLIGENCE

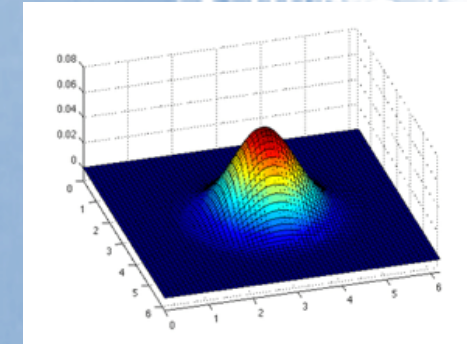
Theoretical model → HPC Application → Results

$$\frac{\partial u}{\partial t} = k \frac{\partial^2 u}{\partial x^2}$$

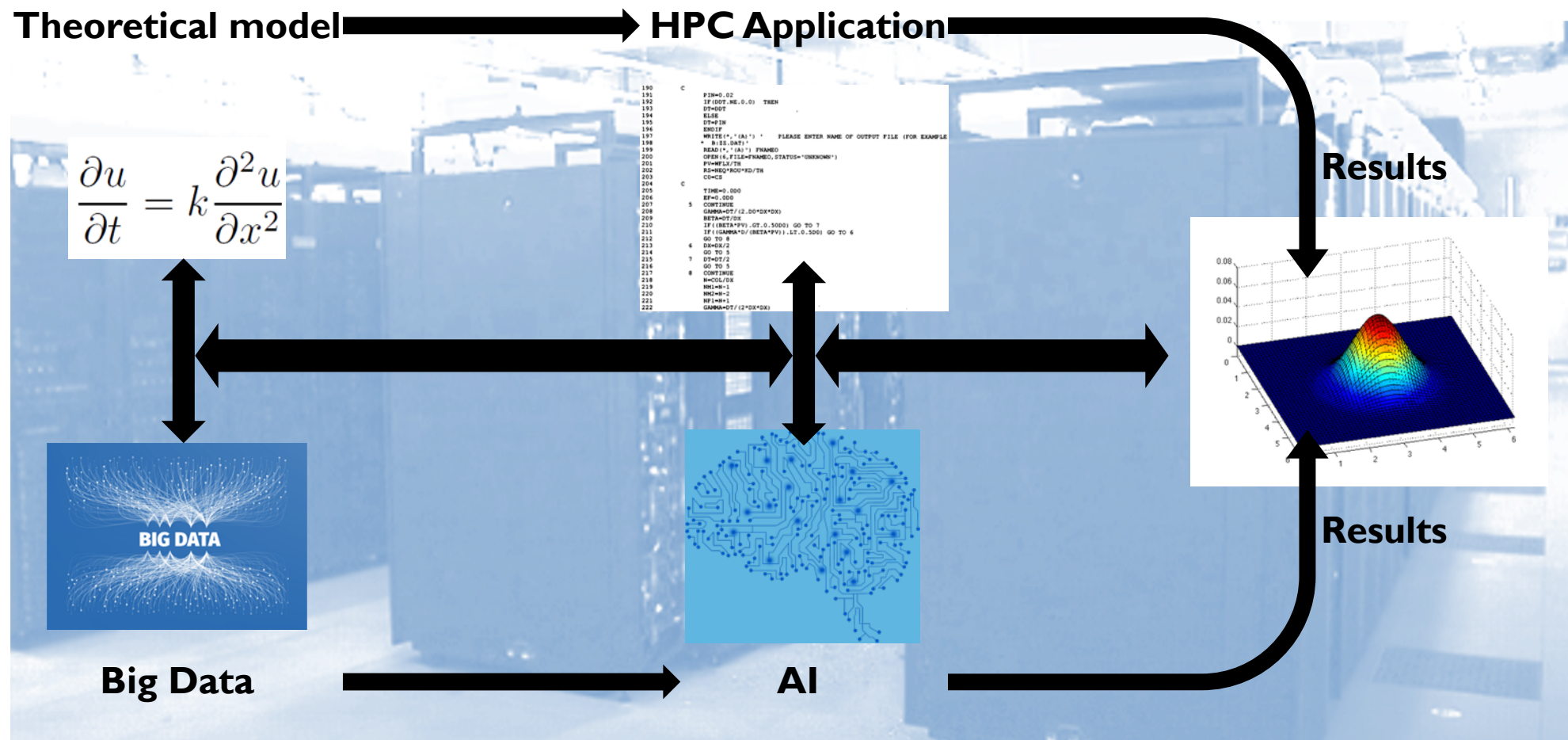
```

190 C
191 FIM=0.02
192 IF (DOT.NE.0.0) THEN
193   DT=DOT
194 ELSE
195   DT=FIM
196 ENDIF
197 WRITE(*, '(A)') ' PLEASE ENTER NAME OF OUTPUT FILE (FOR EXAMPLE
198   ' B:ES.DAT)'
199 READ(*, '(A)') FRAMED
200 OPEN(6, FILE=FRAMED, STATUS='UNKNOWN')
201 FIM=HFILE/TH
202 RS=REQ*ROU*KD/TH
203 CC=CS
204 C
205 TIME=0.000
206 EF=0.000
207 5 CONTINUE
208 GAMMA=DT/(2.00*DX*DX)
209 BETA=DT/DX
210 IF ((BETA*PV).GT.0.5000) GO TO 7
211 IF ((GAMMA*D/(BETA*PV)).LT.0.500) GO TO 6
212 GO TO 8
213 6 DX=DX/2
214 GO TO 5
215 7 DT=DT/2
216 GO TO 5
217 8 CONTINUE
218 N=COL/DX
219 NN1=N-1
220 NN2=N-2
221 NP1=N-1
222 GAMMA=DT/(2*DX*DX)

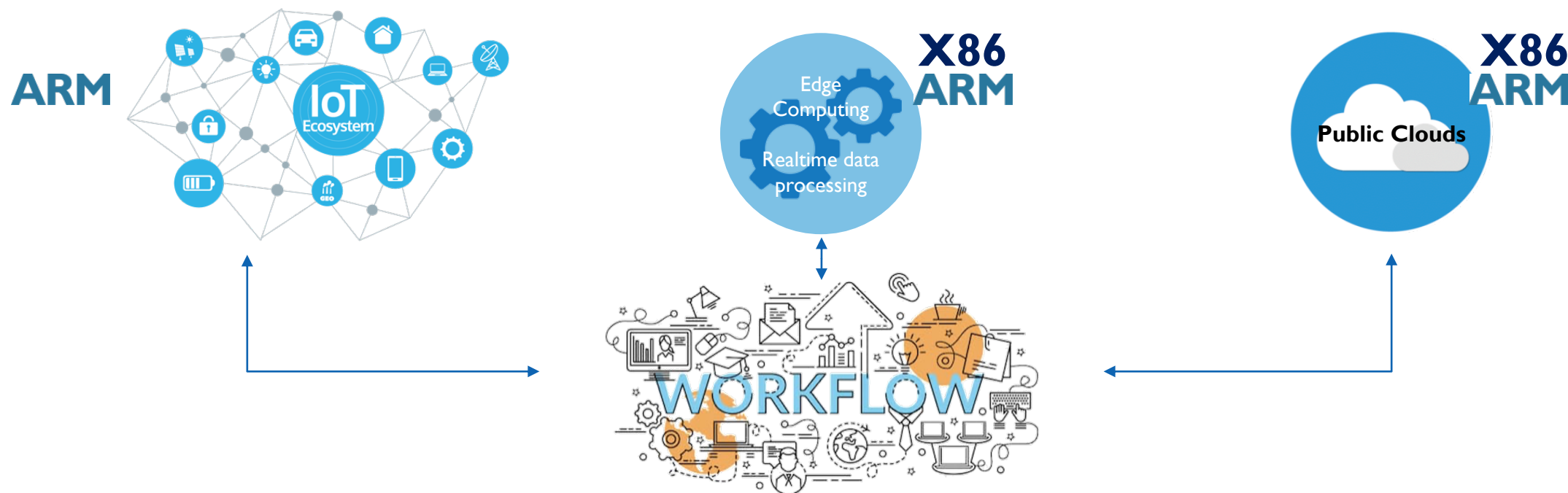
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HPC WITH ARTIFICIAL INTELLIGENCE



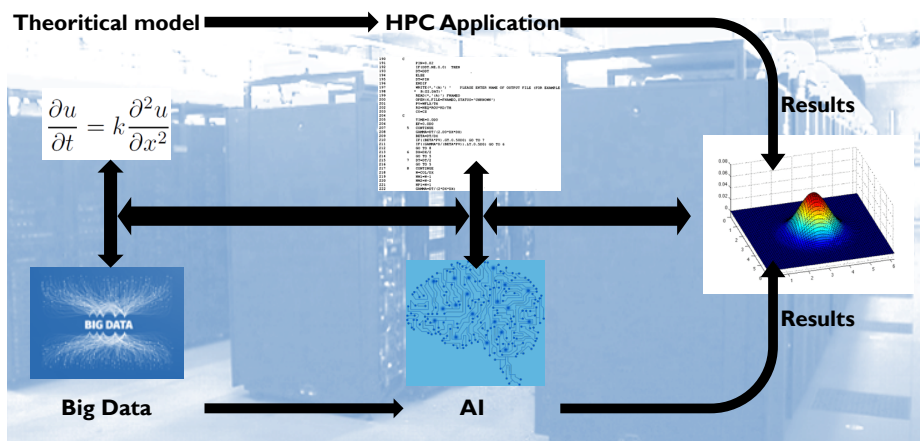
HPC & AI AT EXASCALE: IT'S ALL ABOUT WORKFLOWS (1/3)



SUMMIT



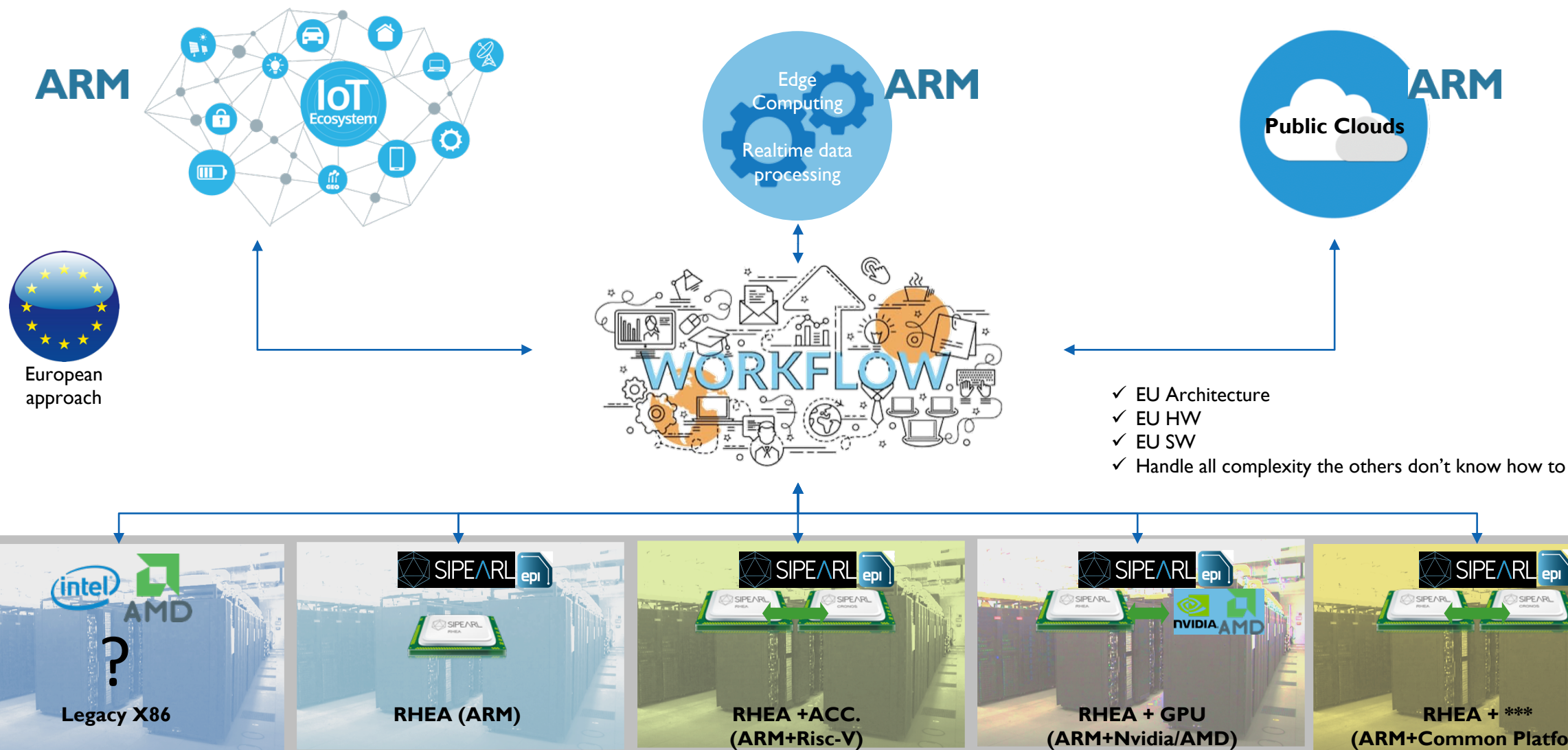
sunway taihulight



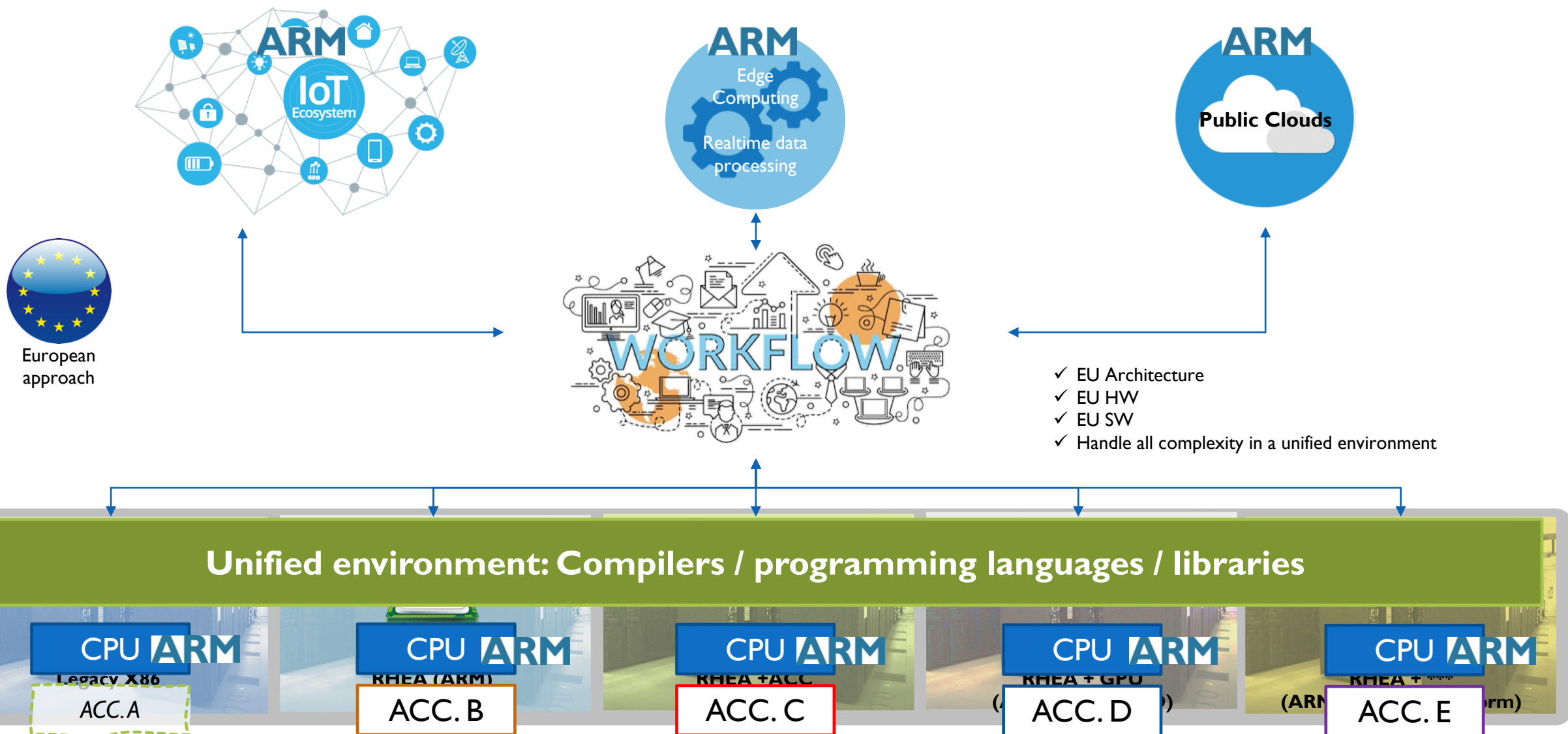
FUGAKU



HPC & AI AT EXASCALE: IT'S ALL ABOUT WORKFLOWS (2/3)



HPC & AI AT EXASCALE: IT'S ALL ABOUT WORKFLOWS (3/3)



TAKEAWAY #1

Exascale and post-Exascale superpercomputers will modular.

They'll have massively non-homogenous architectures, combining one general purpose processor with several different accelerator kinds



TAKEAWAY #2

Software will play an even more important role as a unification layer between all technologies, between all modules

- Opensource and standardization are more important than ever
- Proprietary SW stacks, especially for specialized HW will become problematic



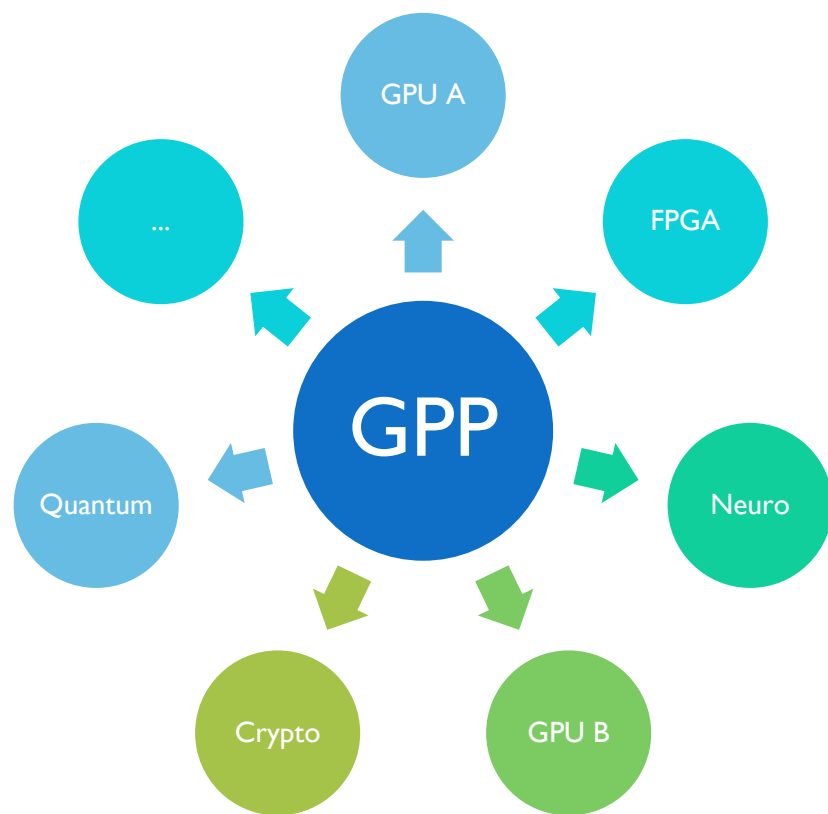
(POST) EXASCALE PROCESSOR SPECIFICATIONS



TAKE AWAYS #1 & #2 CONSEQUENCES

**General Purpose Processors
have to be (much) more open**

**The race to FLOPS is now in the
accelerators area**



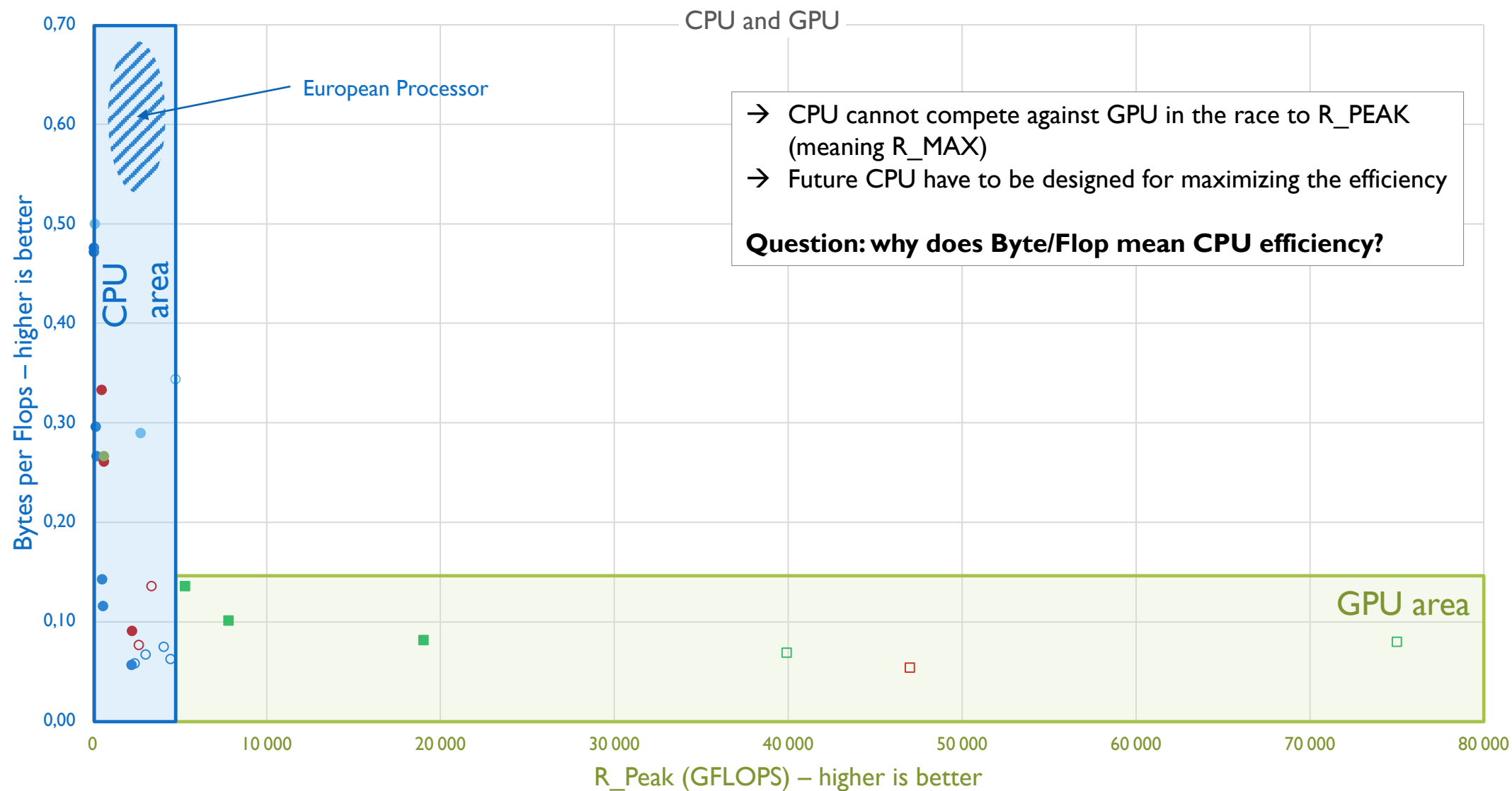
TAKEWAY #3

SPECIFICATION FOR EXASCALE GENERAL PURPOSE PROCESSORS (PART 1)

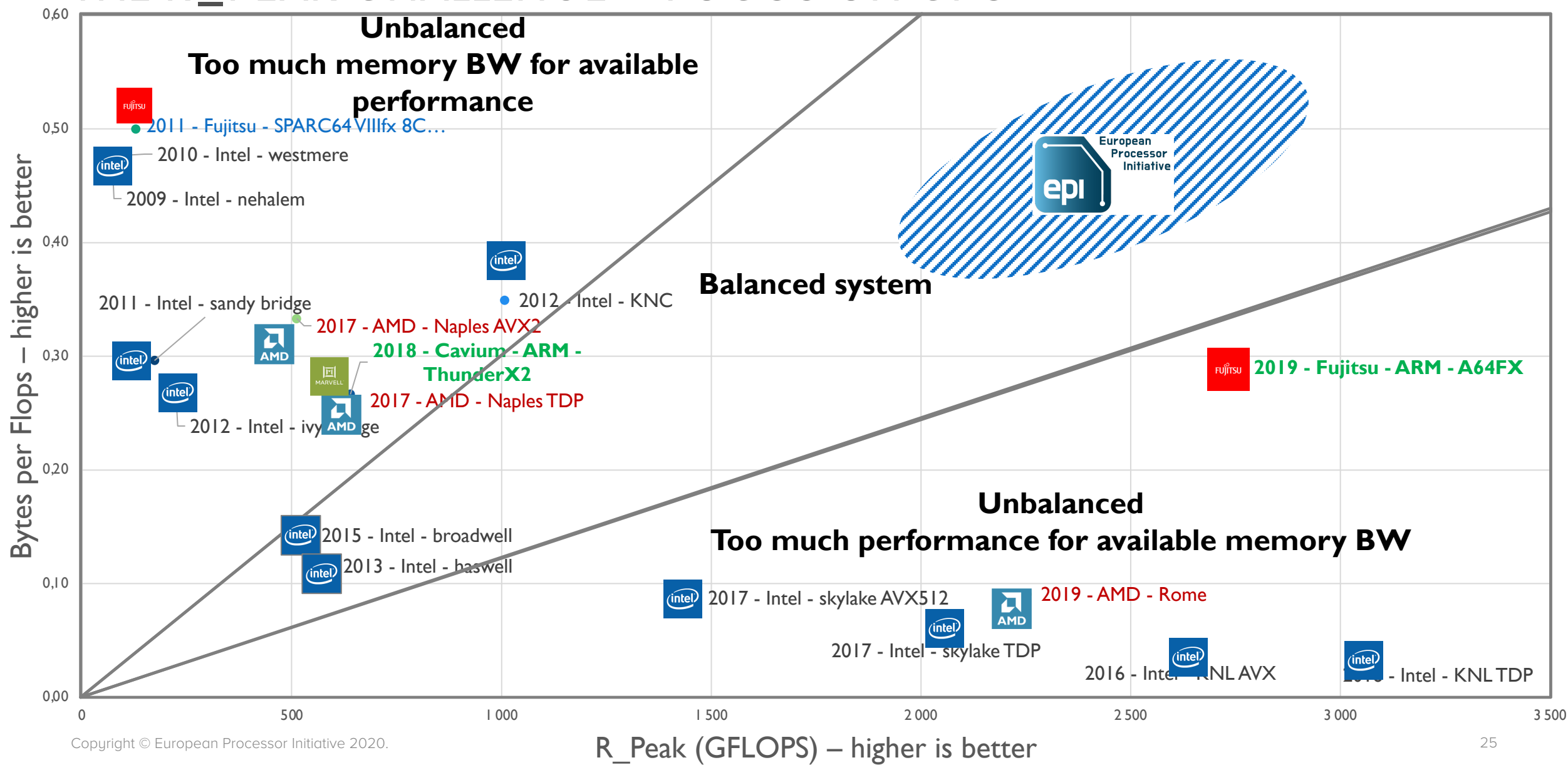
- Need extreme flexibility and performances on external links
 - Composable architectures, from 1 to ≥ 4 sockets (CCIX and/or CXL)
 - HBM 2e / 3
 - *and* DDR 5
 - *and* PCIe G5
 - *and* CXL
- Transparent integration in end-to-end dataflow : IoT \leftrightarrow Edge \leftrightarrow Datacenter \leftrightarrow Cloud
 - Easy to port / optimize
 - Opensource tools
 - Unified development tools

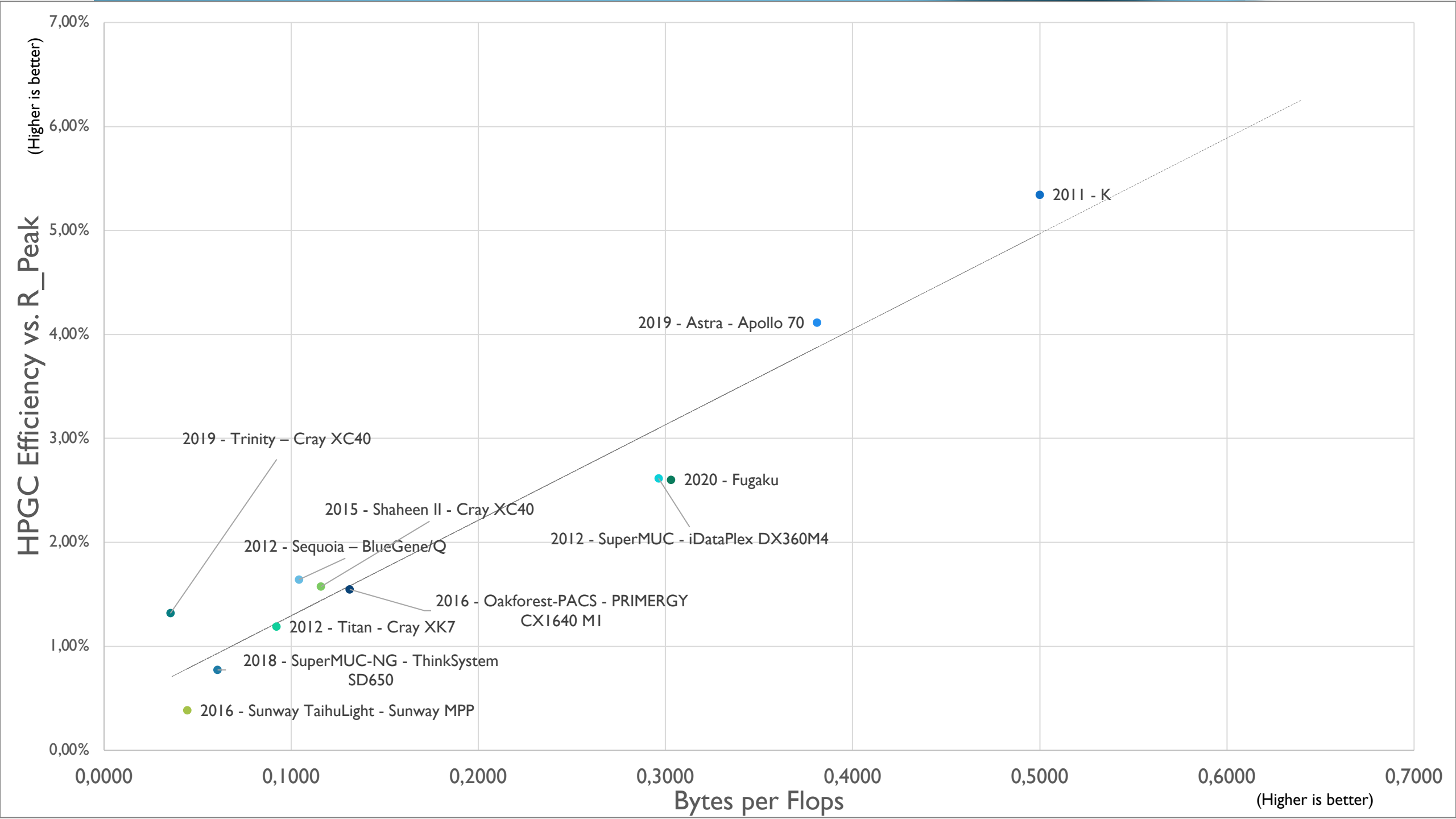


THE R_PEAK CHALLENGE – CPU VS. GPU



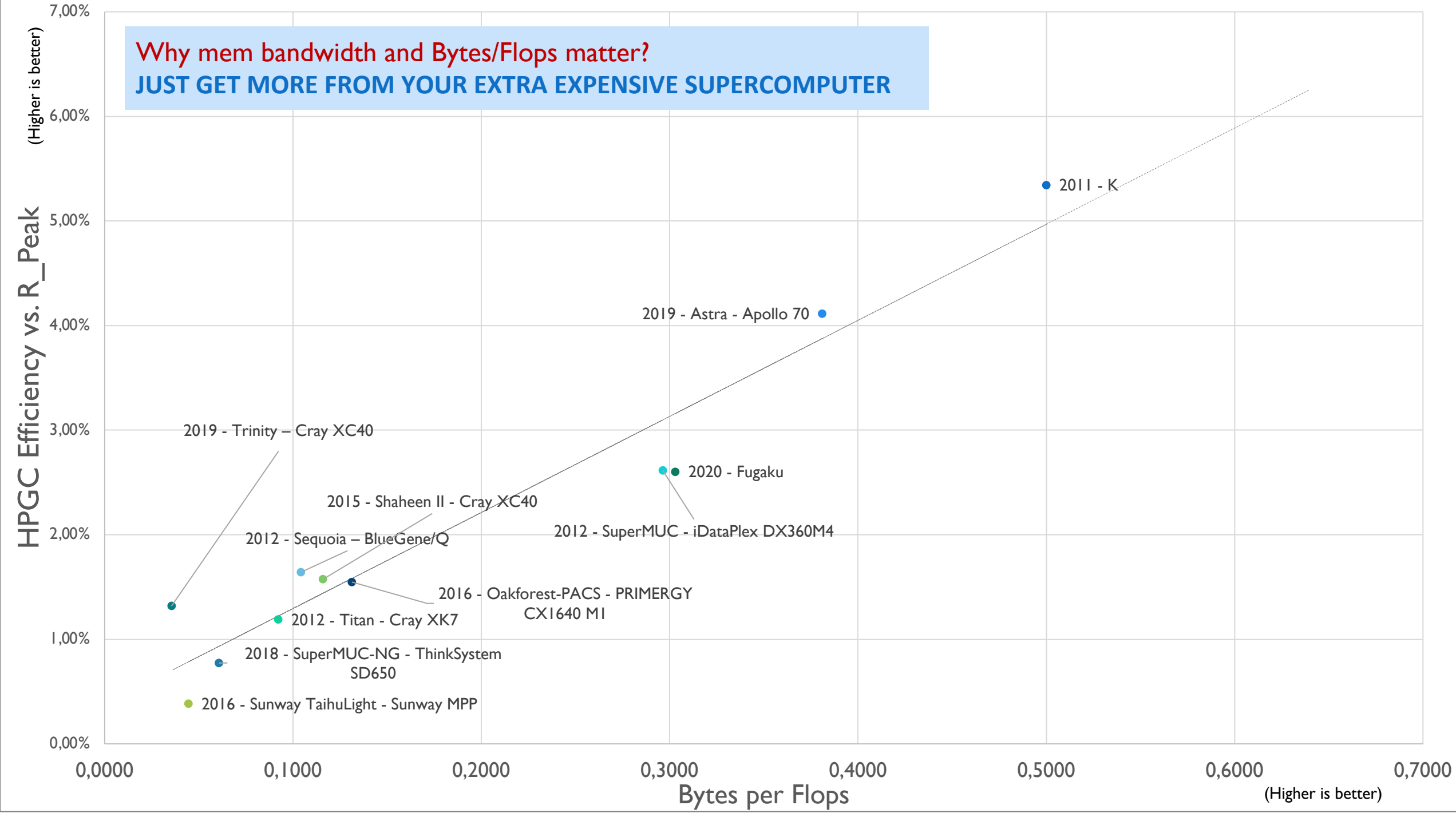
THE R_PEAK CHALLENGE – FOCUS ON CPU



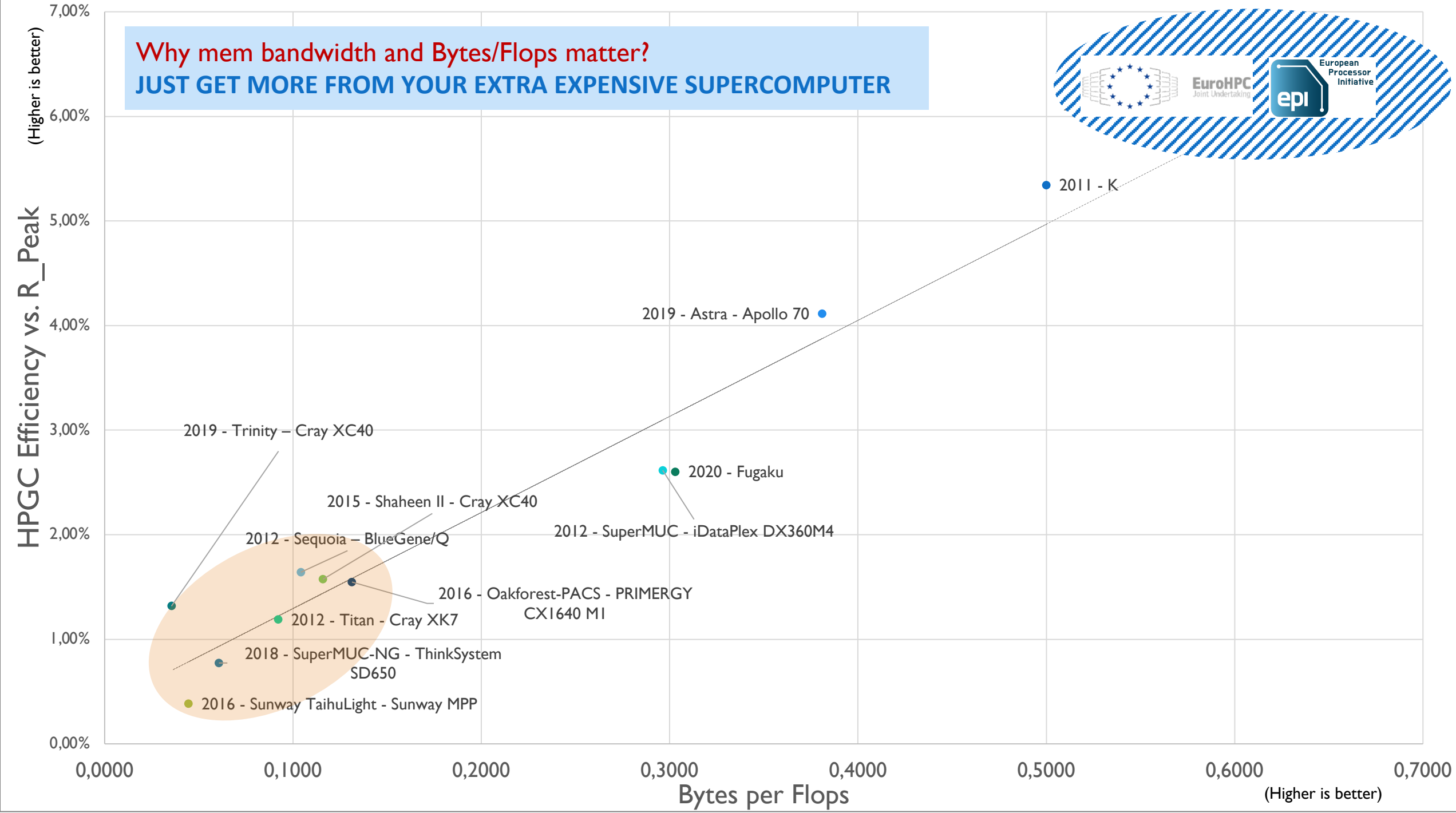


Why mem bandwidth and Bytes/Flops matter?

JUST GET MORE FROM YOUR EXTRA EXPENSIVE SUPERCOMPUTER



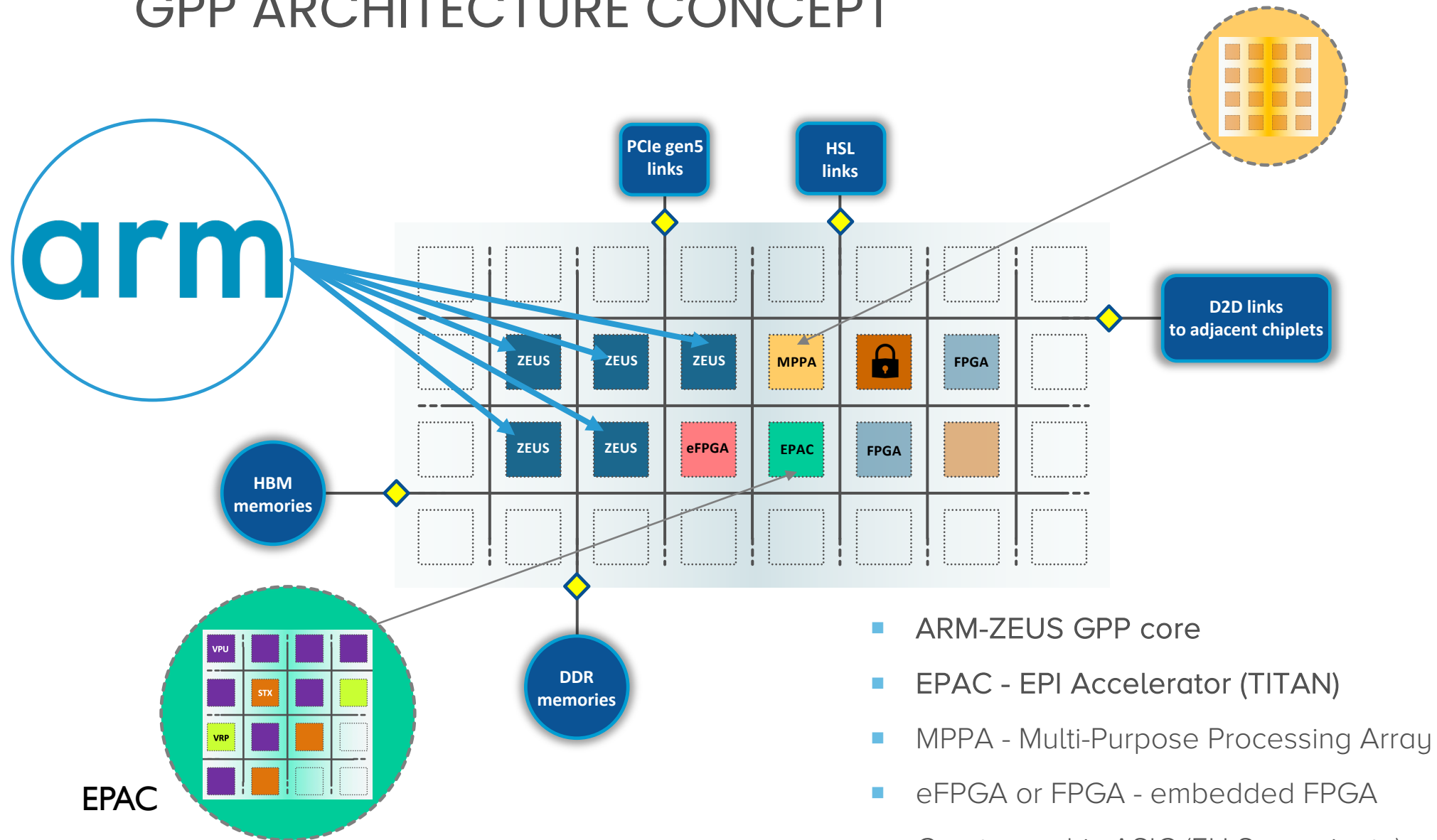
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SO... WHAT TO EXPECT FROM AN EXASCALE GENERAL PURPOSE PROCESSOR? (PART 2)

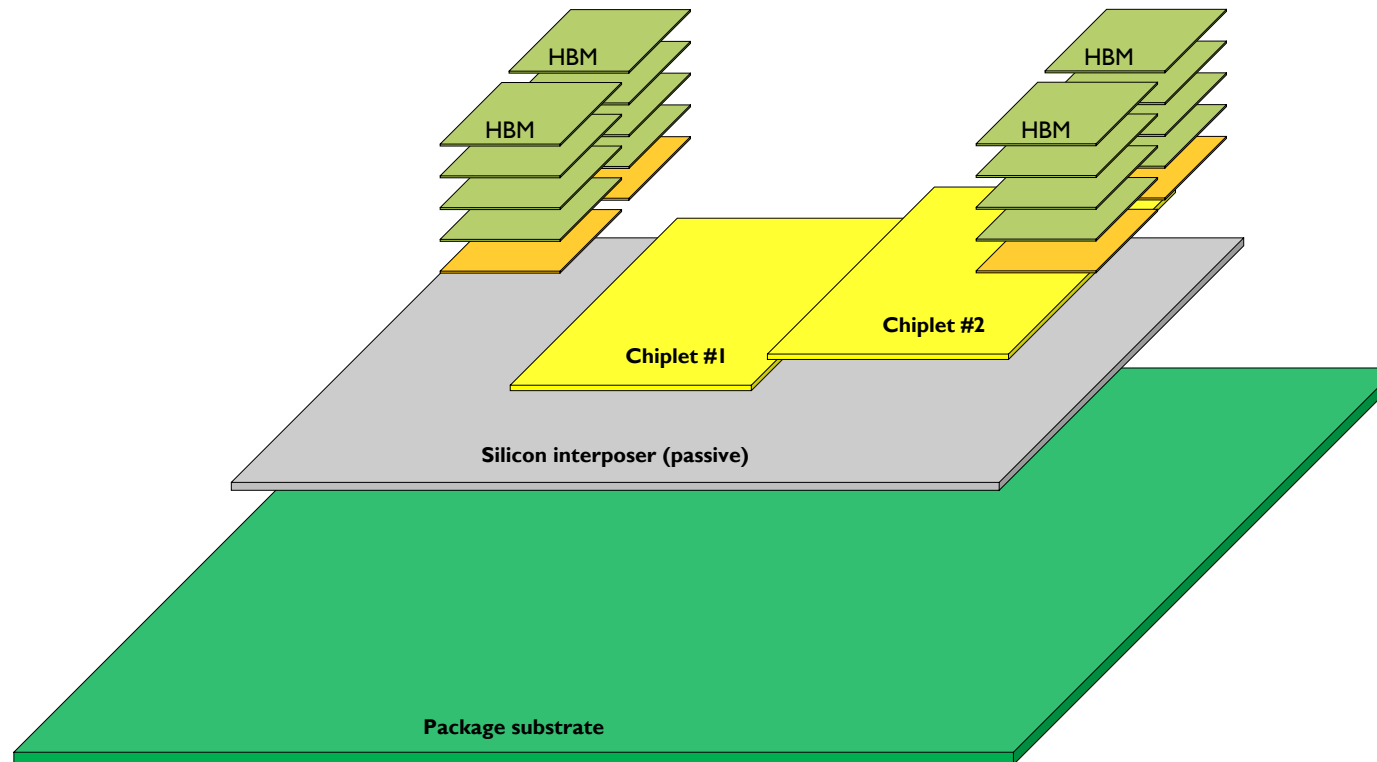
- World class manufacturing process (7nm or better)
- Need extreme flexibility and performances on external links
 - Composable architectures, from 1 to ≥ 4 sockets (CCIX and/or CXL) HBM 2e / 3
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- Transparent integration in end-to-end dataflow : IoT \leftrightarrow Edge \leftrightarrow Datacenter \leftrightarrow Cloud
 - Easy to port / optimize
 - Opensource tools
 - Unified development tools
- **Need “good enough” FP64 performances.
No need to compete with specialized devices like GPUs**
- **Change the metric. Need much better byte/Flop ratio than today**

GPP ARCHITECTURE CONCEPT

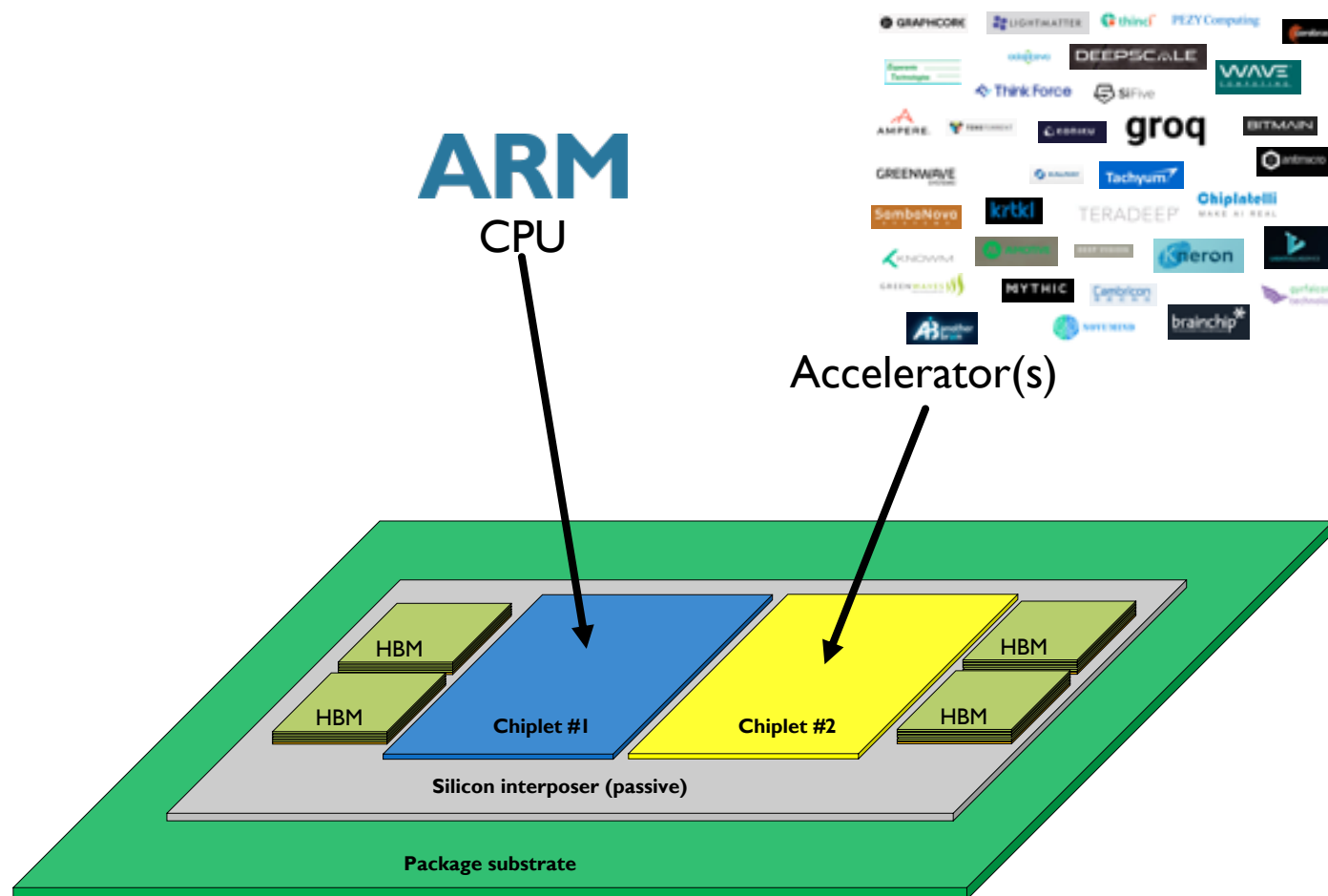


- ARM-ZEUS GPP core
- EPAC - EPI Accelerator (TITAN)
- MPPA - Multi-Purpose Processing Array
- eFPGA or FPGA - embedded FPGA
- Cryptographic ASIC (EU Sovereignty)

CONCEPT OF COMMON PLATFORM : INTERPOSER & MULTI-CHIPLET

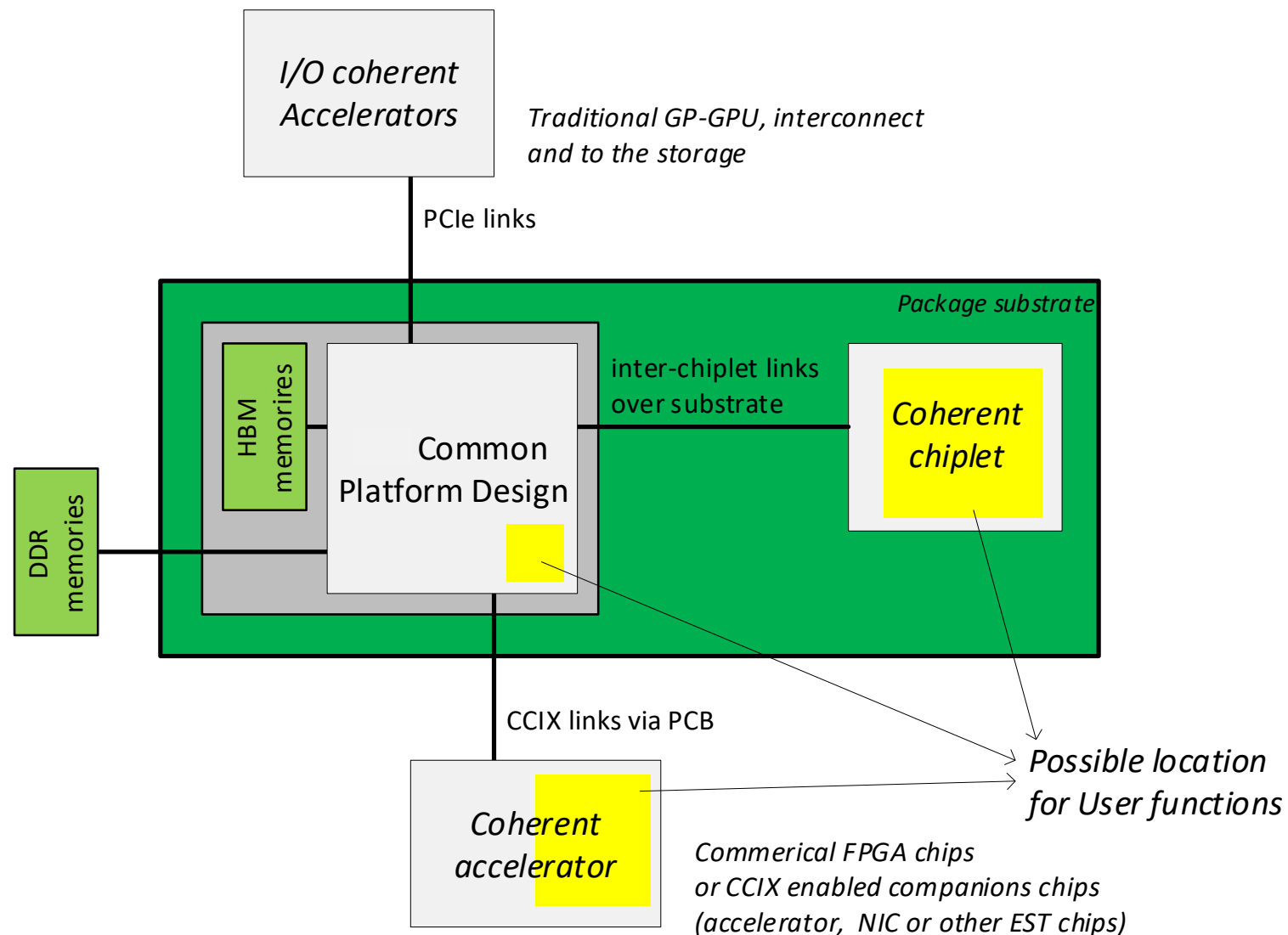


CONCEPT OF COMMON PLATFORM : INTERPOSER & MULTI-CHIPLET



HETEROGENEOUS INTEGRATION

- Integrating customized functions at different levels
- EPI accelerator IPs today are integrated in Rhea design



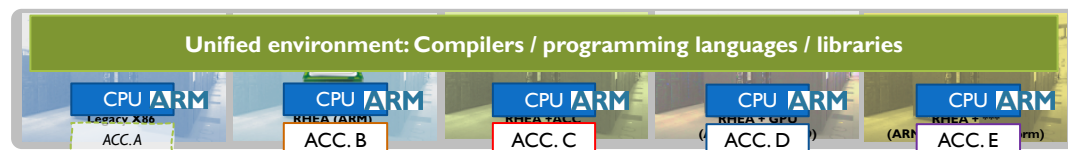
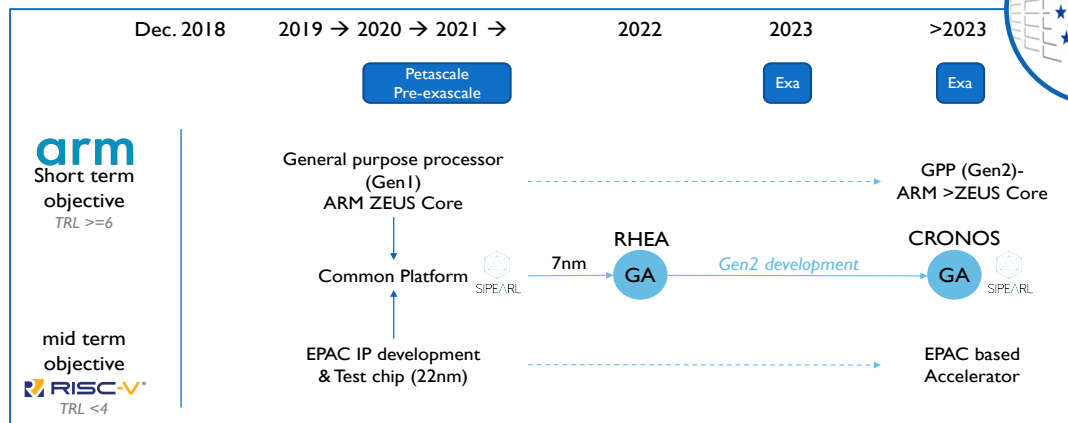
SO... WHAT TO EXPECT FROM AN EXASCALE GENERAL PURPOSE PROCESSOR? (PART 3)

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- Transparent integration in end-to-end dataflow : IoT \leftrightarrow Edge \leftrightarrow Datacenter \leftrightarrow Cloud
 - Easy to port / optimize
 - Opensource tools
 - Unified development tools
- Need “good enough” but excellent FP64 performances.
No need to compete with specialized devices like GPUs
- Need much better byte/Flop ratio than today
- **Based on multi-die and IO-DIE building blocks, combined at package level**

WRAP-UP



FINAL TAKEAWAYS



Exascale and post-Exascale supercomputers will modular.

They'll have massively non-homogenous architectures, combining one general purpose processor with several different accelerator kinds

Software will play an even more important role as a unification layer between all technologies, between all modules

- Opensource and standardization are more important than ever
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THANK YOU FOR YOUR ATTENTION



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